



**Collaboration Meeting
MVD Subgroup
GSI, March 3, 2009**

Thomas Würschig

**Update on the MVD mechanics
and presentation of a concept for
the strip disks**



MVD mechanics meeting

MVD Mechanics Meeting

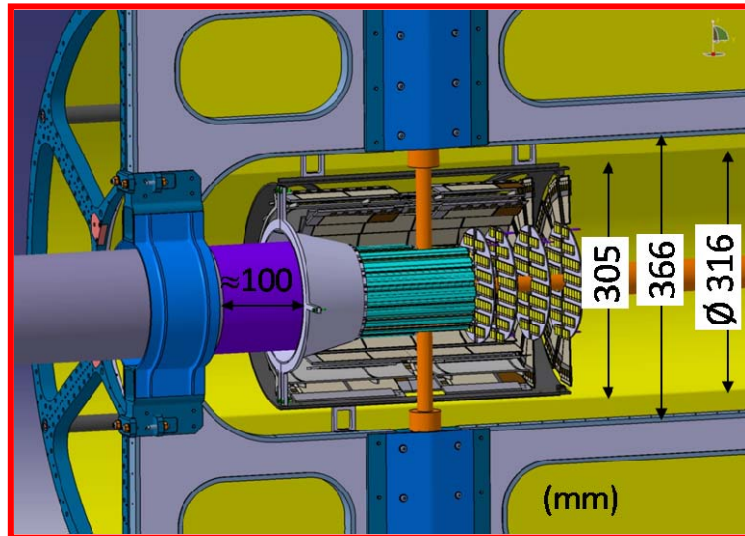


- Jülich, February 9-10, 2009
 - Participants
 - ✓ T. Stockmanns, H. Jäger (IKP, FZ Jülich)
 - ✓ D. Grunwald (ZAT, FZ Jülich)
 - ✓ G. Giraudo (INFN Torino)
 - ✓ L. Lambrecht (IKV Aachen)
 - ✓ Th. Würschig (HISKP, Uni Bonn)
 - Program
 - ✓ Status in Bonn / Jülich / Torino; Presentation of IKV Aachen
 - ✓ Discussion:
Pixel design / Strip design / Cooling and integration / CAD conventions, CAD converter / Next steps and missing info

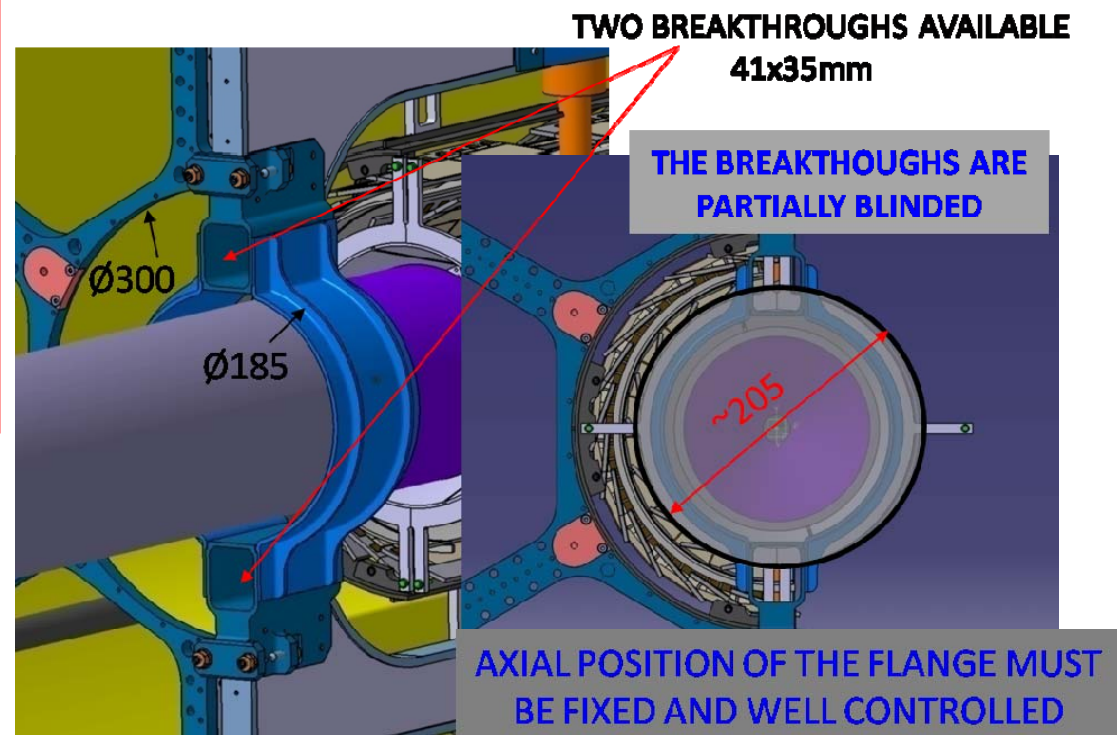
MVD Mechanics Meeting



- Communication with Frascati
 - Interface Central frame (CF) ↔ MVD ↔ (STT)



G. Giraud, D. Orecchini

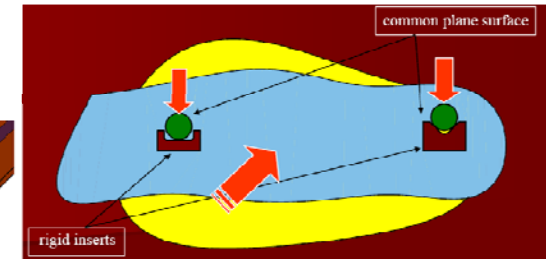
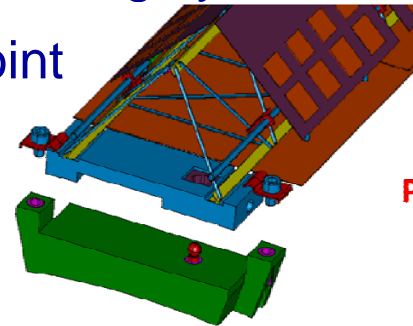


- ✓ Updated version of CF
- ✓ 41 x 35 mm² area at top and bottom over full length left for readout

MVD Mechanics Meeting

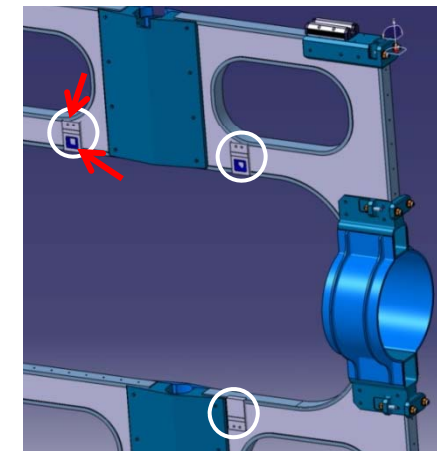
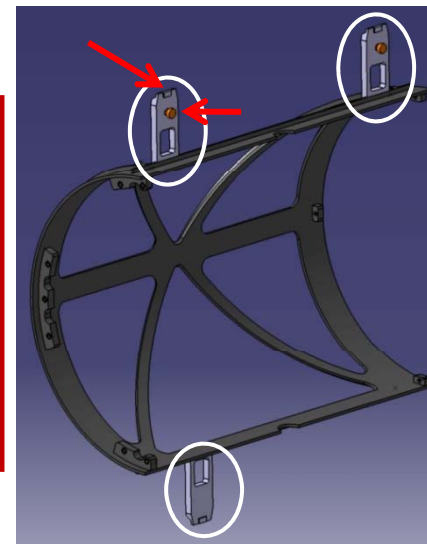
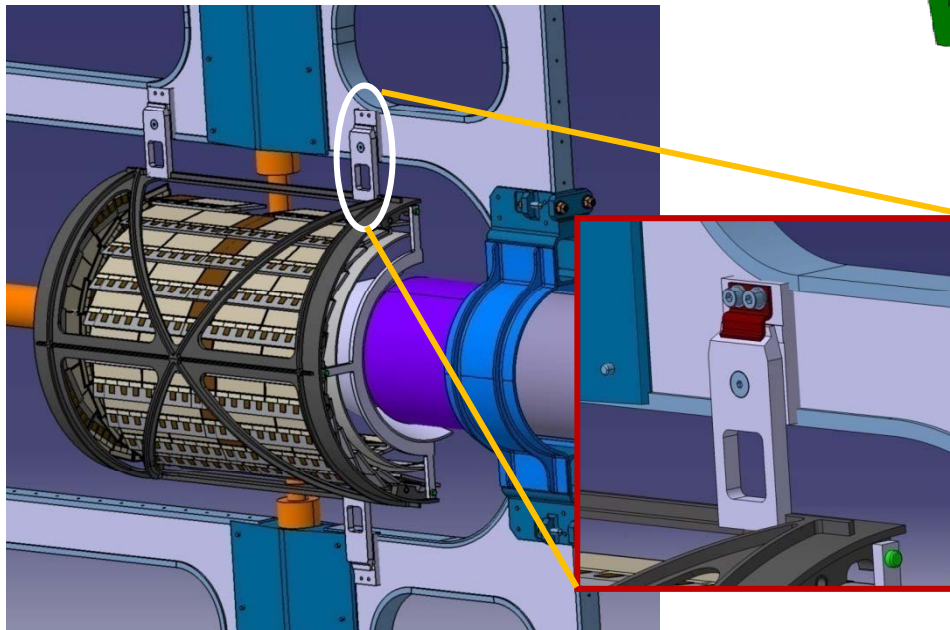


- Proposal for MVD coupling to CF
 - Based on ALICE ladder repositioning system
 - 2 fixed points @ top and 3rd point @ bottom define a plane



Precision < 6 μm

The SDD and SSD support structure for the ALICE Inner Tracking System.
G. Giraudo et al. 2009 JINST 4 P01003

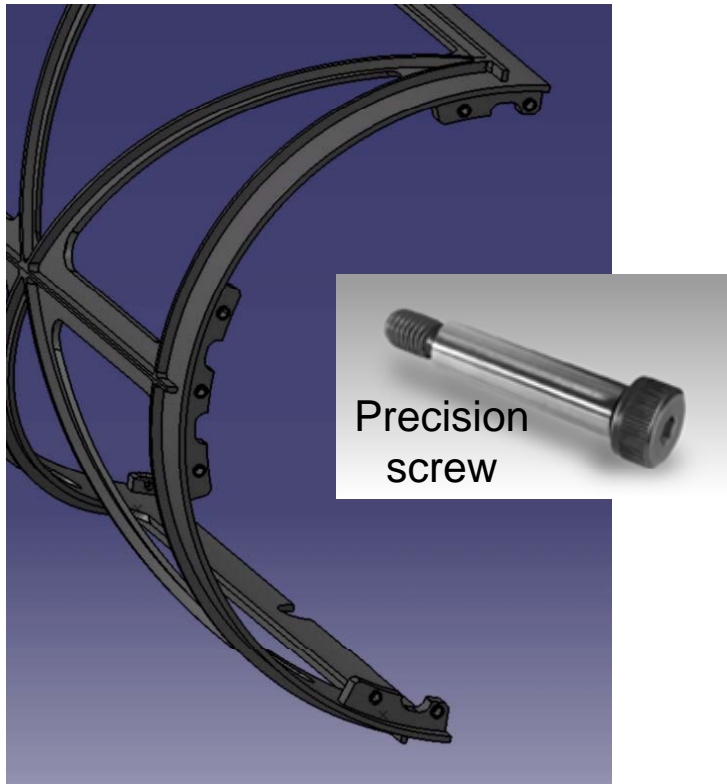


MVD Mechanics Meeting



- MVD global support ↔ barrel support
 - Common design for strip and pixel subsystem

G. Giraud

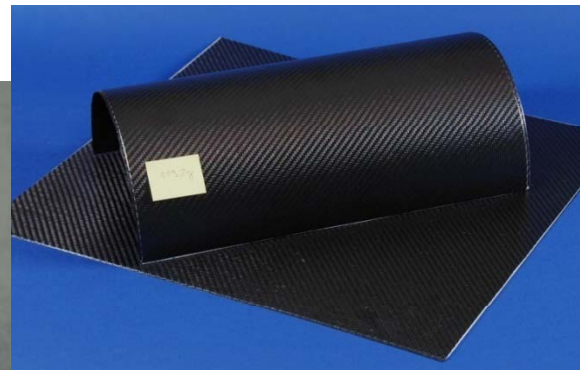
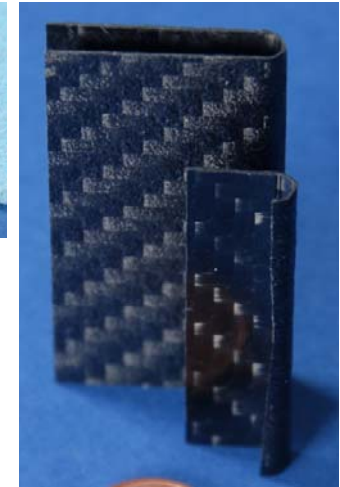
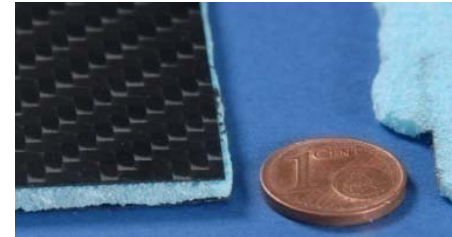


- Three fixing points for pixels
Screw:
1 x M4 + 2 x precision M4
- Four fixing points for strips
Screw:
2 x M4 + 2 x precision M4

MVD Mechanics Meeting



- Carbon structure processing
 - Stave support: Sandwich structure (Carbon – Foam – Carbon)
 - Barrel support: Half-shell and saw-tooth support
 - 1st water cutting



*D. Grunwald,
L. Lambrecht*

MVD Mechanics Meeting

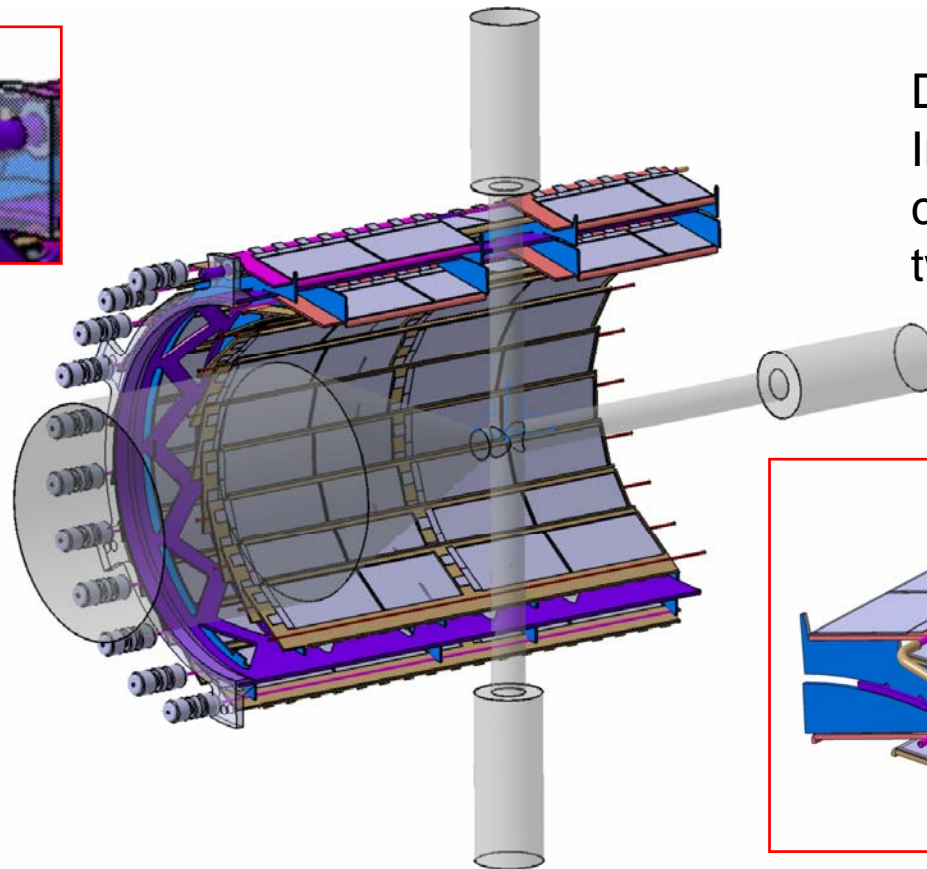


- Strip barrel design

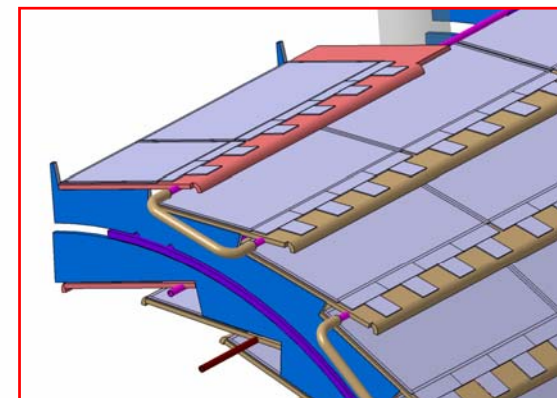
D. Grunwald



Upstream:
Lead trough
connections for
cooling pipes



Downstream:
Interconnection of
cooling pipes for
two super-modules



MVD Mechanics Meeting

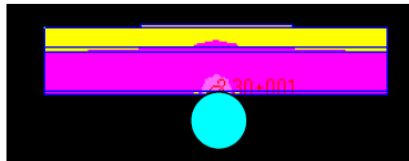


- Preliminary thermal simulations for pixel modules

S. Coli

THERMAL SIMULATIONS:

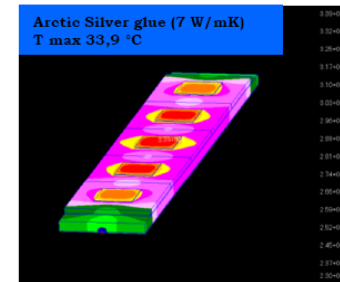
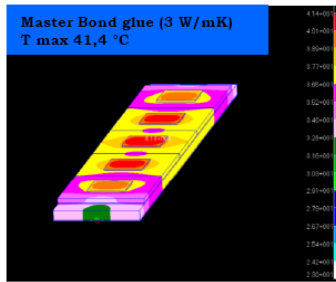
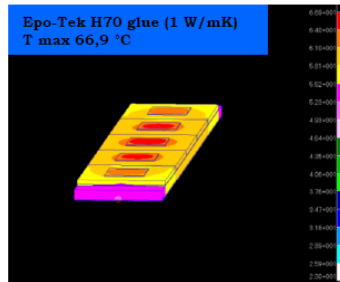
➤ Coolant: Water (18°C)



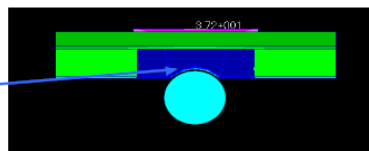
FIRST TEST MODEL:

Dummy FEE: 0,5 mm Alumina (20 W/mK) + 0,1 mm with Power: 5W
 Glue layer: 0,1 mm (Epo-Tek H70, Master Bond EP30AN, Arctic Silver)
 Carbon foam: 1 mm (40 W/mK)
 Glue layer: 0,1 mm (Epo-Tek H70, Master Bond EP30AN, Arctic Silver)
 Cooling water 18°C (about 23°C on the wall). Flow rate : 0,3 l/min
 MODEL LENGHT: 50 mm

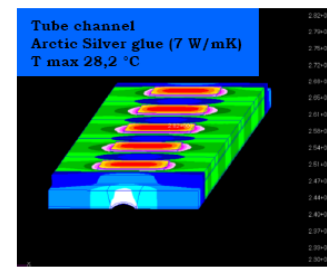
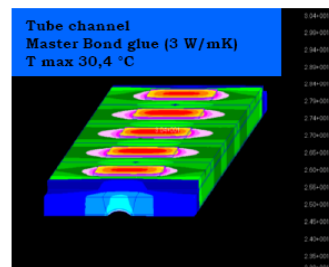
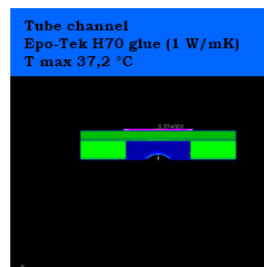
Different Thermal glues



Improving contacts



Better contact and different glues

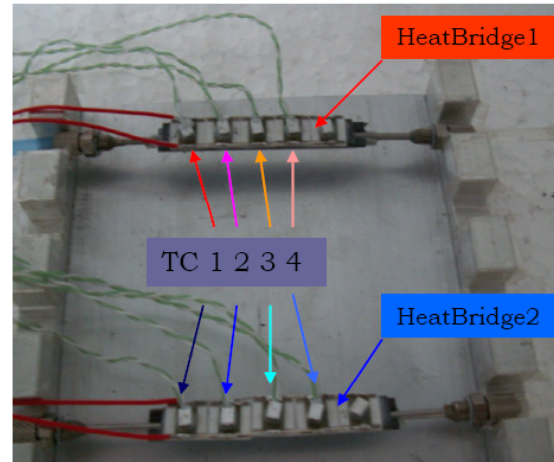
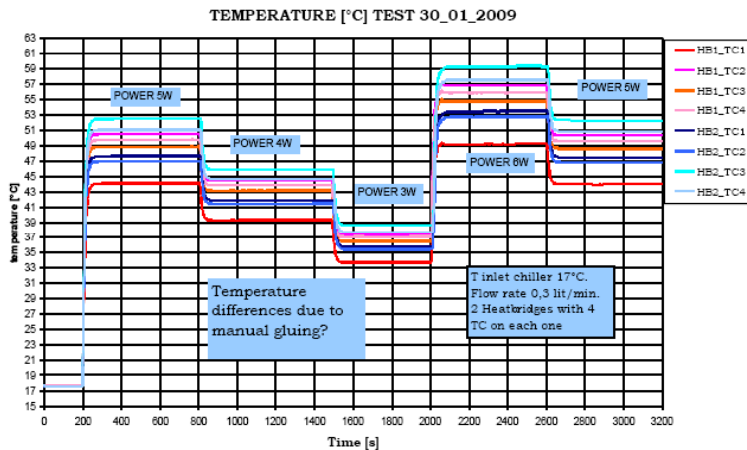


- Improved contact with elliptical pipe
- Best results for silver glue
- BUT:
- Comparable results for standard glue (Epo-Tek) with improved contact
- Achieved temperatures:
 $T_{\max} = (28 \dots 37) \text{ } ^\circ\text{C}$

MVD Mechanics Meeting



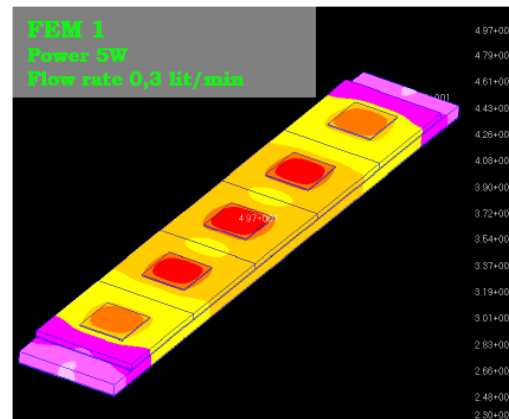
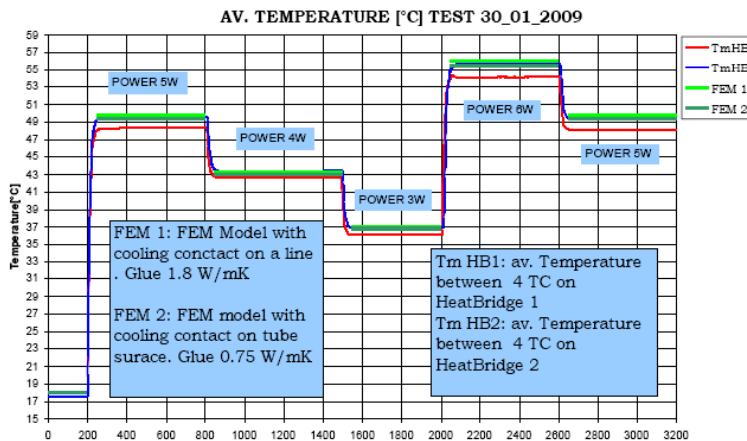
- Thermal measurements: built up and test of 1st prototype



S. Coli

- Good agreement of mean value between FEM analysis and measurement

TEST RESULTS AND FEM MODELS

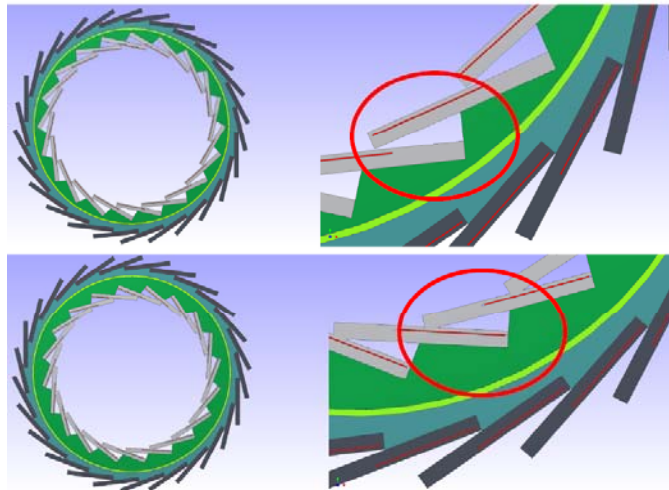


- Still bigger variations for single FEE dummies
- improvement of glue contact

MVD Mechanics Meeting



- Dedicated concept for strip disks ...more details later... *Th. Würschig*
- Design check for proposed modification in barrel 3

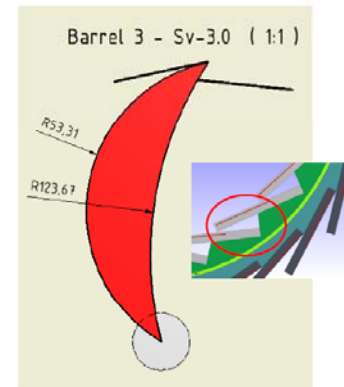


Default:

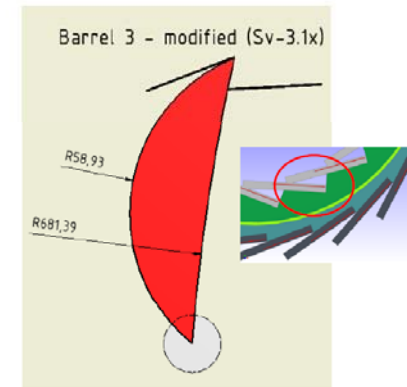
- Sensor at innermost radius
- Readout position at outer radius

Proposed modification:

- Readout at innermost radius
- Sensor position at outer radius



Default:
Maximum bending radius: 124 mm



Proposed modification:
Maximum bending radius 6 x higher!

PROS

- Better access to readout electronic
- ... But: is this really necessary and realistic?
 - ✓ In operation there is NO access to the whole MVD at all
 - ✓ In test phase: fully equipped MVD barrel layer must be taken apart even for the modified version to reach the regions of interest WITHOUT any danger of destroying the neighbouring modules

CONS

- More material load at inner radii
- Higher radial tilting angle for the super-modules
 - Higher variation of radius of the sensor's active area
 - Much bigger gap for bending radii
 - Less space in between subsequent super-modules
- Referring momentum range of the gap in the bending radius reaches a highly populated region of the PANDA experiment!



- **Discussions**

- Pixel design:
 - ✓ Arrangement of pixels in the forward disks
 - ✓ Pixel module types
 - ✓ Cooling
- Strip design:
 - ✓ Arrangement of super-modules in barrel part
 - ✓ Shape of the barrel stave support
 - ✓ Super-module positioning (barrel part)
 - ✓ Cooling
- Integration:
 - ✓ Support for strip disks ↔ global MVD support
 - ✓ Support for strip barrel layers ↔ global MVD support



- **Conclusions: Pixel part**

- Implementation of different module sizes
 - ✓ Different lengths
 - ✓ Number of rows: one or two
 - ✓ Basic unit: 10 mm x 10 mm

→ Number of different module types should be minimized (4 ... 6)

- Work out of two designs

Optimized coverage ↔ Minimized material *

- * Realistic considerations of technical limitations
(e.g. cooling, spatial safety margins)

→ Input to simulations → Results basics for optimisation

- **Conclusions: Pixel part**

- Cooling

- ✓ Coolant: water 18°C

- ✓ Better contacts improve efficiency

- ✓ Water flow does not have such big impact

- ✓ Best cooling temperature for pixel modules roughly 30°C

→ Study of effects for silicon sensors in this temperature region w.r.t. thermal runaway necessary! (also valid for strip part)

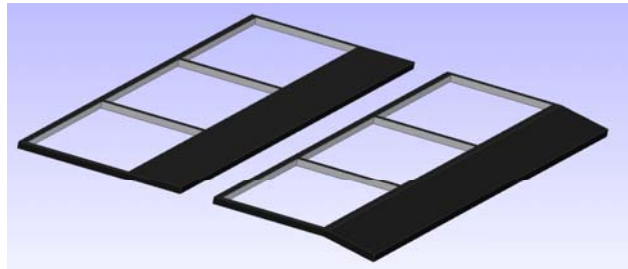
- **Conclusions: Strip part**

- Forward part: New disk concept

→ Best solution for optimized coverage and minimized material budget

- **Conclusions: Strip part**

- Barrel layer: Implementation of modified stave support
 - ✓ Deflection of the plane supporting the FEE + cooling pipe
 - ✓ Deflection angle = tangential tilting of the super-modules



- More radial space and prevention of collision between super-modules (FEE plane || next sensor plan)
- Production feasible in carbon resulting in an even stiffer structure
- Barrel stave positioning
 - ➔ Adaptation of “clip” technology used in ALICE as one option

MVD Mechanics Meeting



- **Conclusions: Integration**

- Forward part
 - Decoupling of pixel and strip part to MVD frame applying new concept
 - *Maybe additional support for pixel disks by strip disk part necessary*
- Barrel part
 - Adaptation of the strip barrel support to the modified MVD frame

- **CAD hierarchy**

	MVD pixel/ strip version
MVD part:	All barrel layer = Hshell (half-shell) All disk layer = Fwd (forward part)
Layer:	All super-modules forming a half-layer → Functional level, (mechanically) not a "real" one
Super-module:	Module + support + cooling pipe → Smallest mechanically independent unit
Module:	Sensor, frontend, cable (maybe additional support) → smallest electronically independent unit (= readout channels) → mechanically (mostly) not independent
Sensor:	Active and passive volume

Concept for the forward silicon strip disks

Concept for strip disks



- Interesting solution for LAMBDA wheel at HERMES experiment
 - Setup:
 - ✓ Double sided trapezoidal strip sensor sensors (DSSD)
(thickness: 300 μm ; stereo angle: 30°; pitch: $\approx 160 \mu\text{m}$)
 - ✓ 2 disk layers with a distance of 5 cm
 - ✓ Inner radius: 9 cm / Outer radius: 33 cm
 - ✓ Severe boundary conditions ($R_{\text{max}} = 34 \text{ cm}$)
 - ✓ FEE: 0.4 W / 128 channel (HELIX chip)

Concept for strip disks



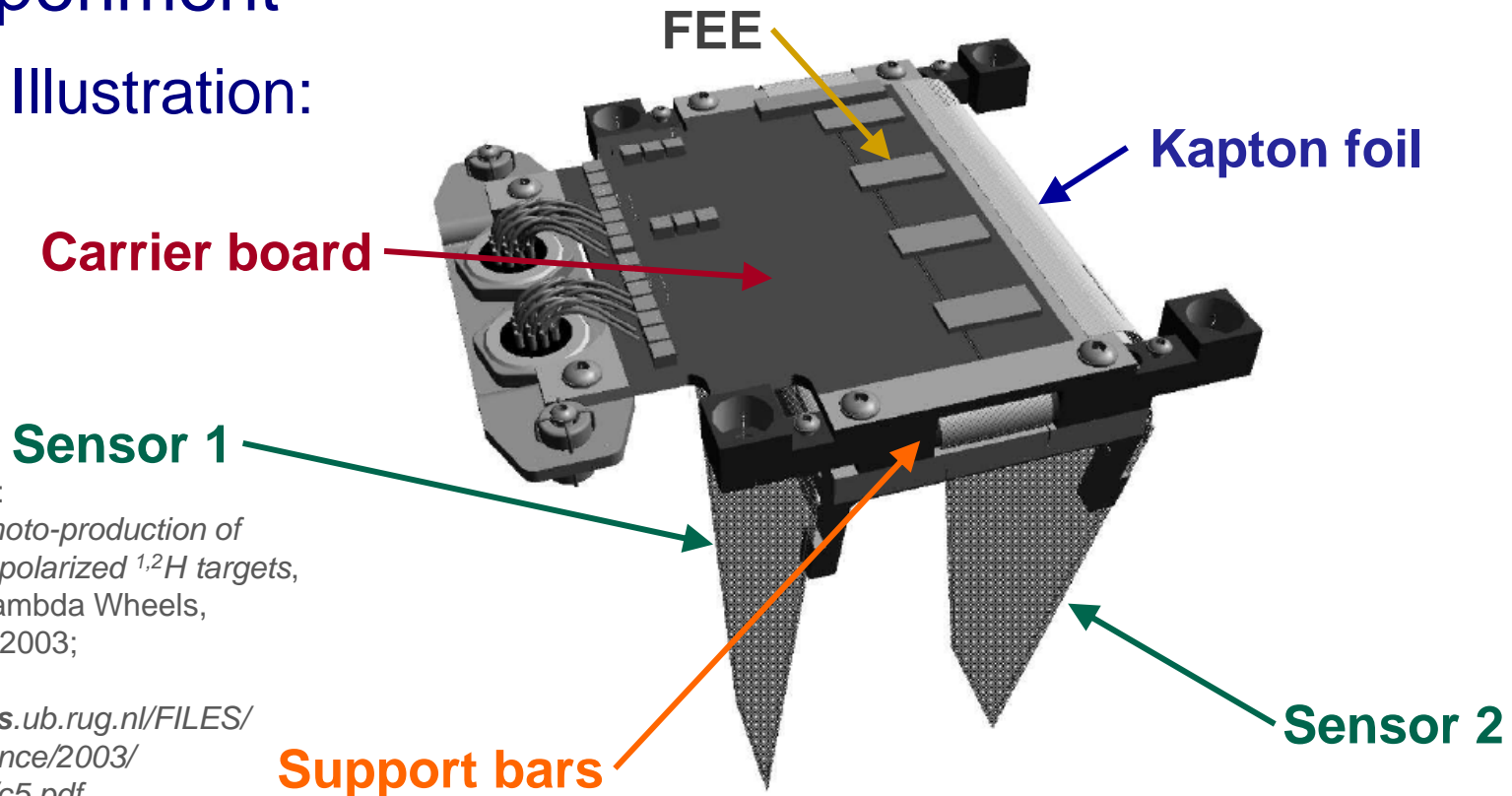
- Interesting solution for LAMBDA wheel at HERMES experiment
 - Concept:
 - ✓ **Wire bonding** (17 μm Al):
sensor \leftrightarrow **capton foil** \leftrightarrow FEE
 - ✓ **Carrier board** (multi layer Kapton-Copper *OFHC*)
for each sensor
 - ✓ Carrier boards connected to **support (bars)** to form a rigid structure
 - ✓ Connection of these (super-)modules to **outer frame**

Concept for strip disks



- Interesting solution for LAMBDA wheel at HERMES experiment

- Illustration:



D.Heesbeen:

Quasi-real photo-production of hyperons on polarized $^{1,2}H$ targets,
Chapter 5: Lambda Wheels,
Dissertation, 2003;

Link:

dissertations.ub.rug.nl/FILES/faculties/science/2003/d.heesbeen/c5.pdf

Figure 5.2: Computer aided drawing of a Lambda Wheels silicon detector module.

Concept for strip disks



- Interesting solution for LAMBDA wheel at HERMES experiment

- Illustration:

D.Heesbeen:

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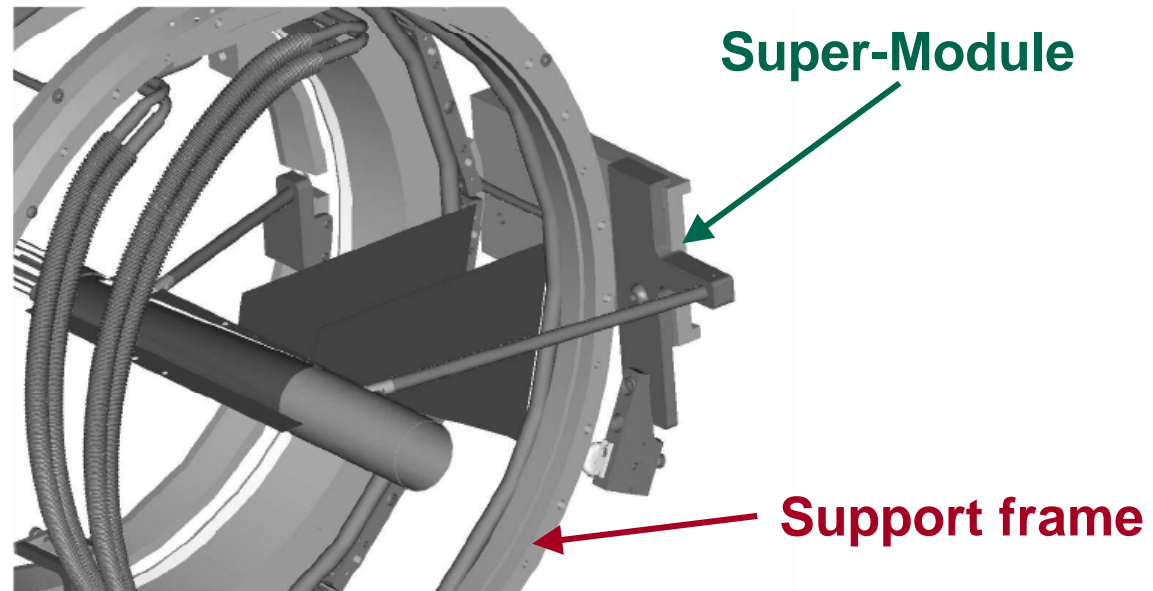


Figure 5.1: Computer aided drawing of the frame of the Lambda Wheels with one module installed for ease of reference. The lepton beam enters the tapered wake field suppressor from the left.

Concept for strip disks



- Adaptation of the HERMES concept for the strip disks of the MVD (incl. additional forward disks)

WHY?

➤ Similar conditions

- ✓ $R_{\max} = 34 \text{ cm} \leftrightarrow 28 \text{ cm}$ (MVD)
- ✓ Layer distance like for MVD
- ✓ Sensor dimensions + pitch $\sim \frac{1}{2}$ size for MVD
- ✓ Same number of frontend chips
- ✓ Comparable global support concept: frame

➤ Existing prototypes show feasibility of the concept!

Details:

dissertations.ub.rug.nl/FILES/faculties/science/2003/d.heesbeen/c5.pdf



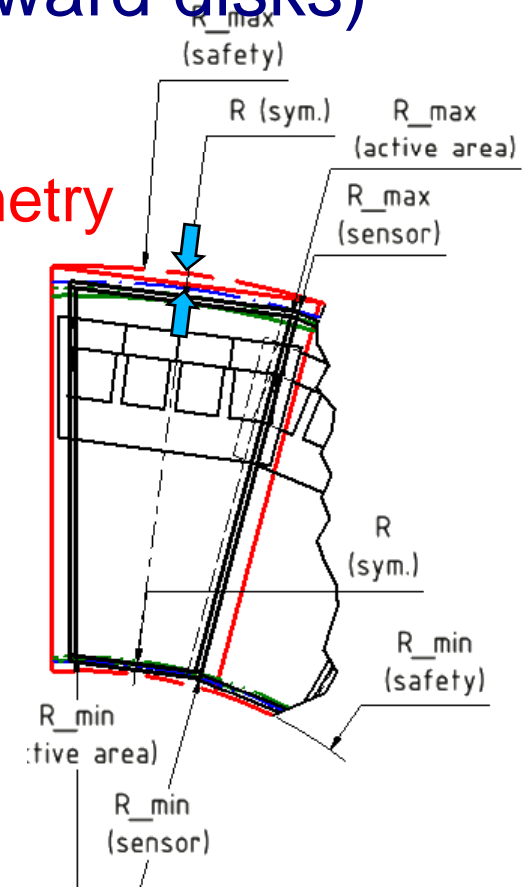
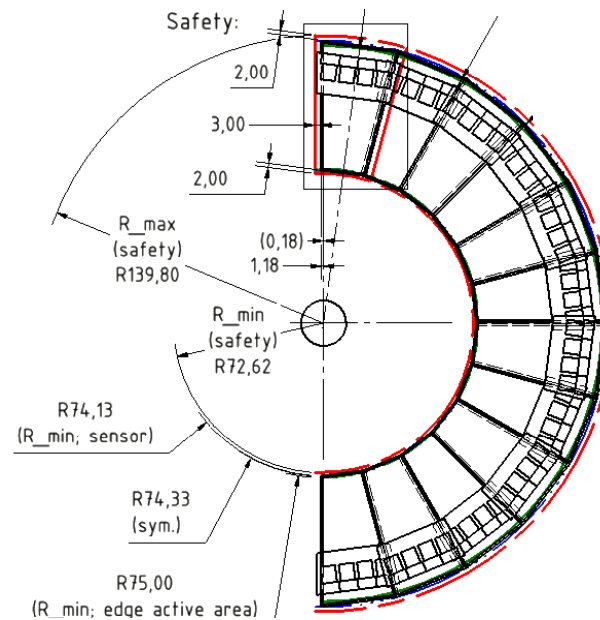
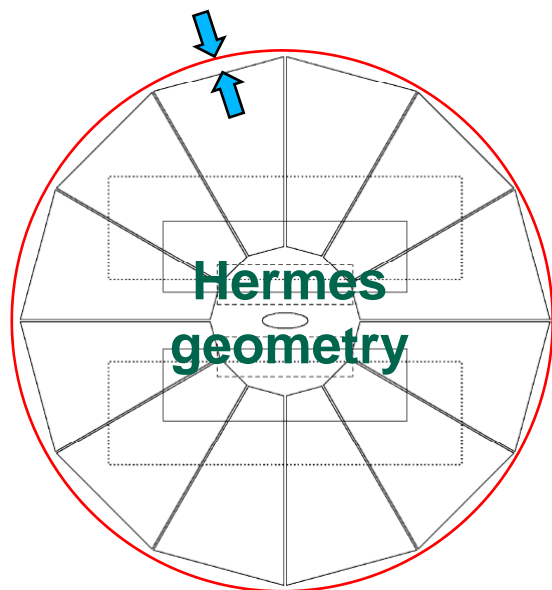
Concept for strip disks



- Adaptation of the HERMES concept for the strip disks of the MVD (incl. additional forward disks)

What is different?

- Smaller margin to R_{max} \rightarrow 24 fold geometry



Concept for strip disks

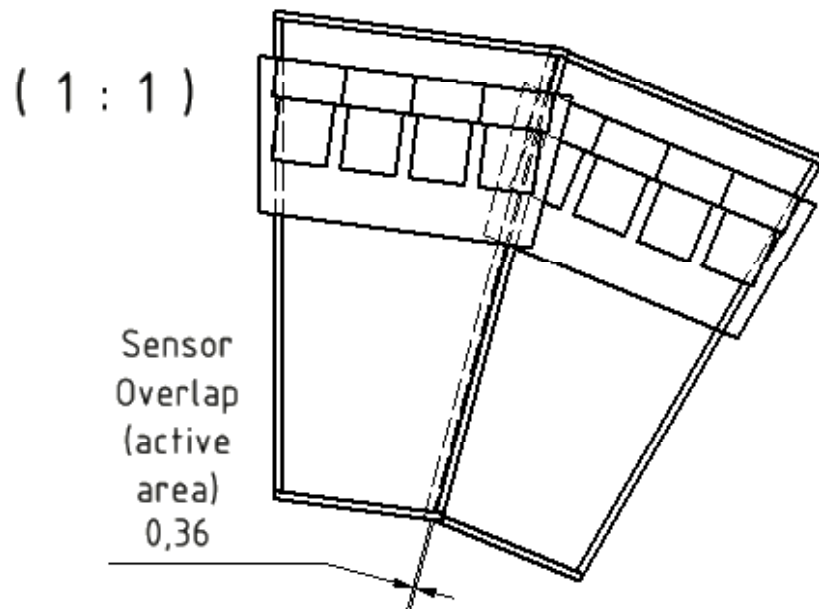


- Adaptation of the HERMES concept for the strip disks of the MVD (incl. additional forward disks)

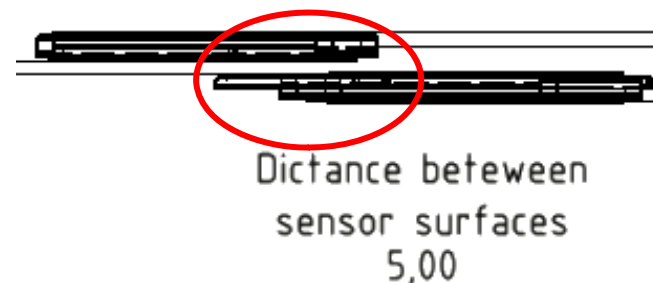
What is different?

➤ Sensor overlap

→ Shift of subsequent sensor



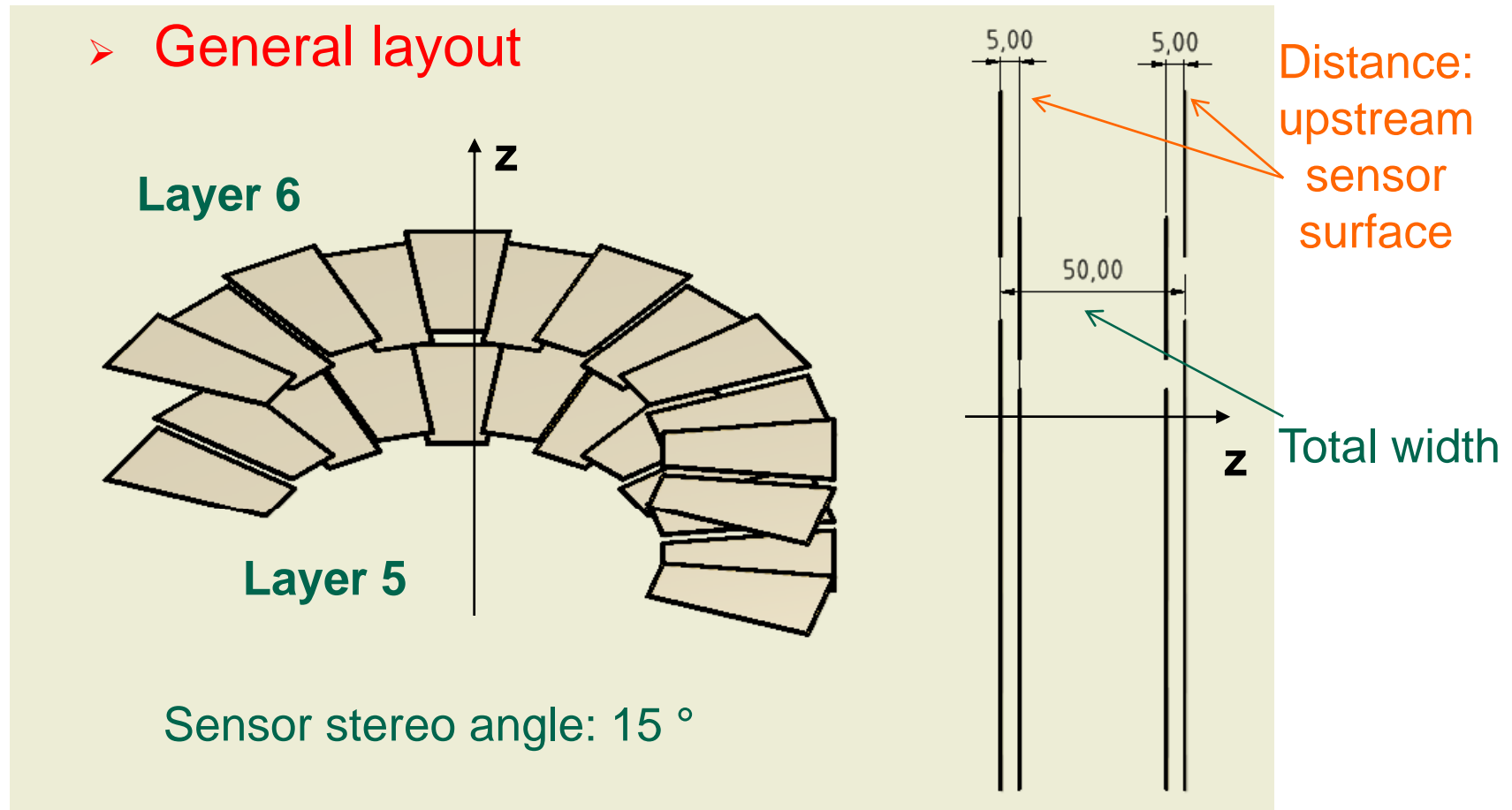
→ Two different z-position within one disk layer



Concept for strip disks



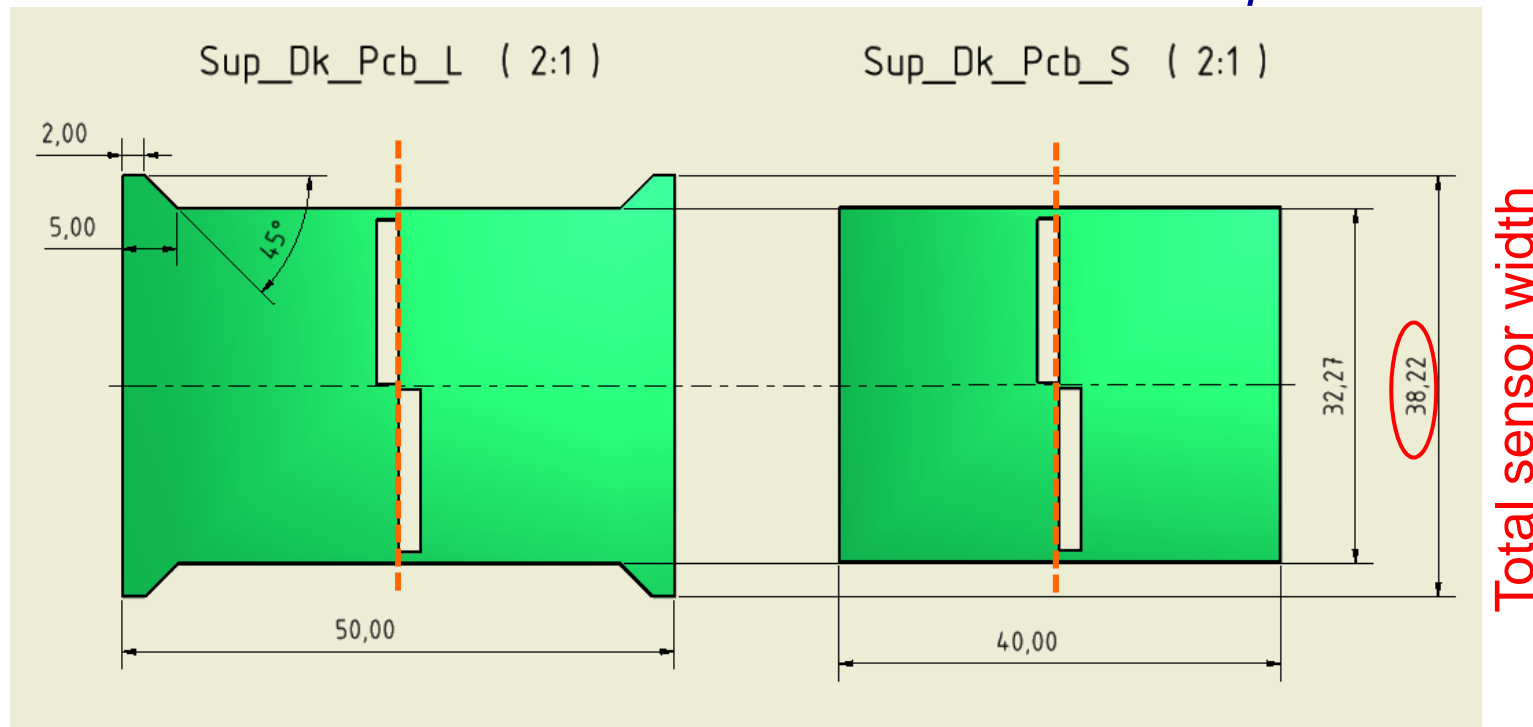
- Implementation of the new disk concept



Concept for strip disks



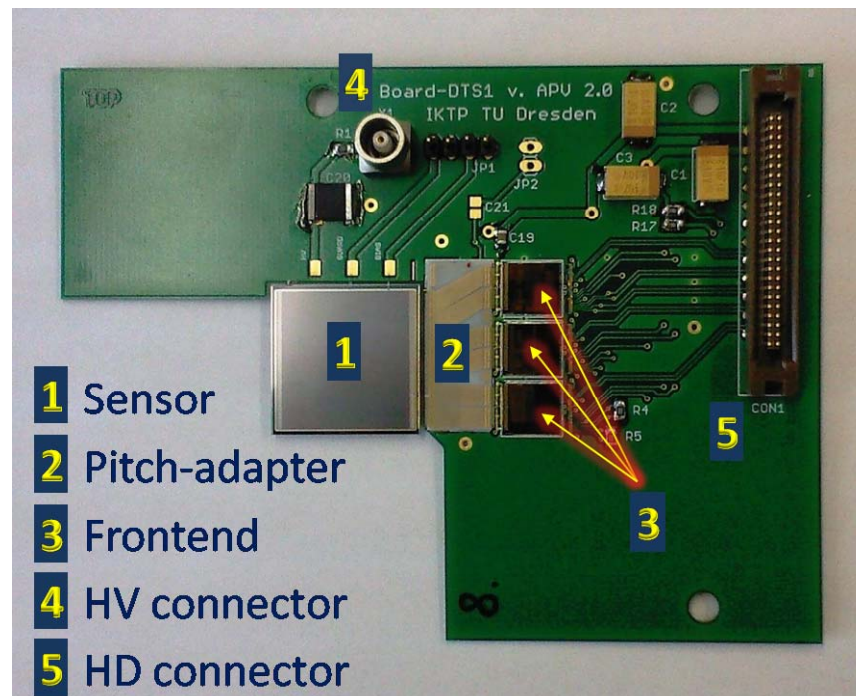
- Implementation of the new disk concept
 - 2 carrier board with different shapes
 - ✓ Complete readout for both sensors
 - ✓ *Later: Modifications for 1 carrier board / sensor possible*



Concept for strip disks



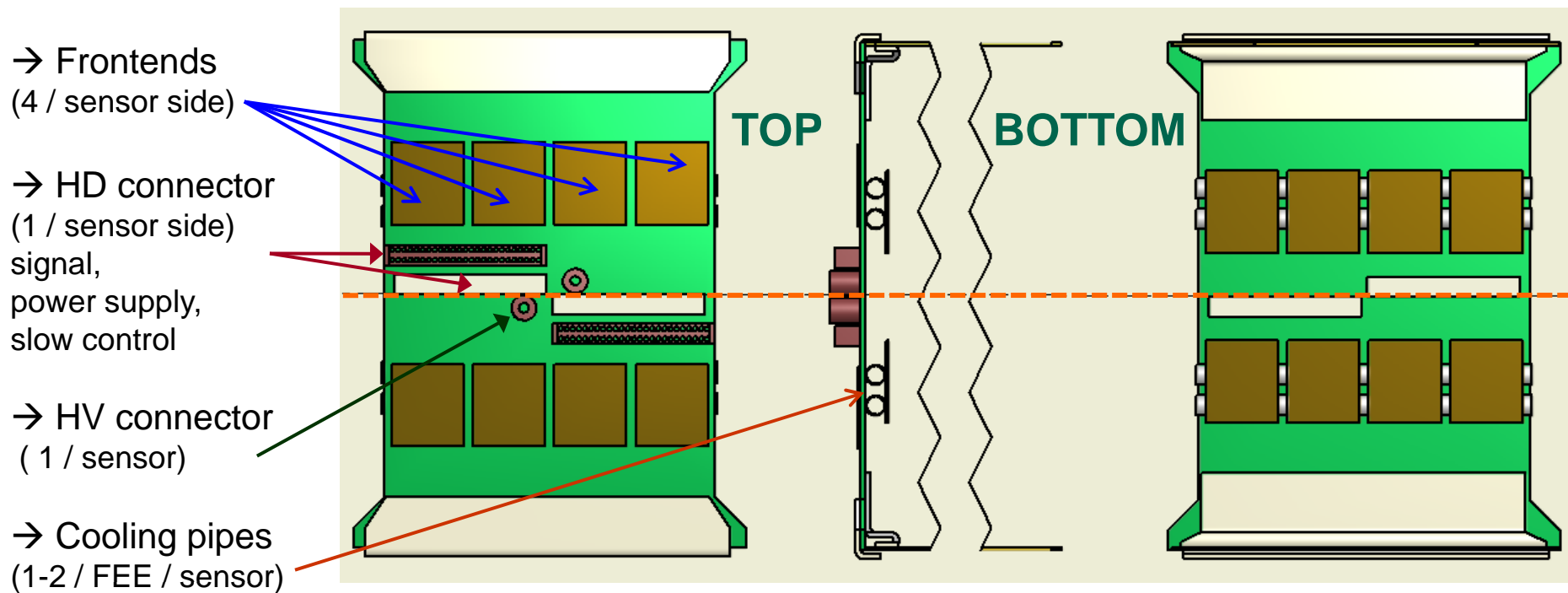
- Implementation of the new disk concept
 - Equipped carrier boards
 - ✓ Master prototype: DTS L-board



Concept for strip disks



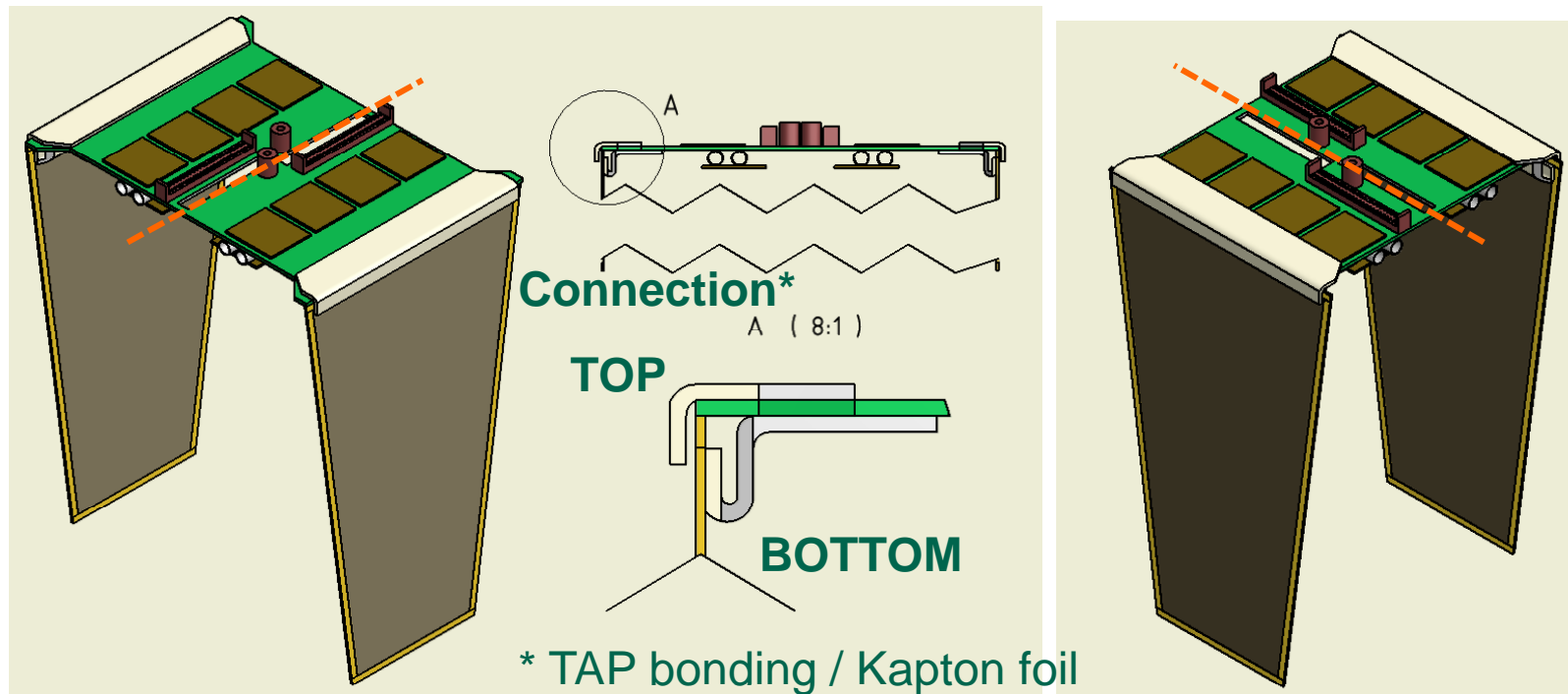
- Implementation of the new disk concept
 - **Equipped carrier boards**
 - ✓ Complete readout for both sensors
 - ✓ *Later: Modifications for 1 carrier board / sensor possible*



Concept for strip disks



- Implementation of the new disk concept
 - **Module: Equipped carrier boards + connected sensors**
 - ✓ Complete readout for both sensors
 - ✓ *Later: Modifications for 1 carrier board / sensor possible*

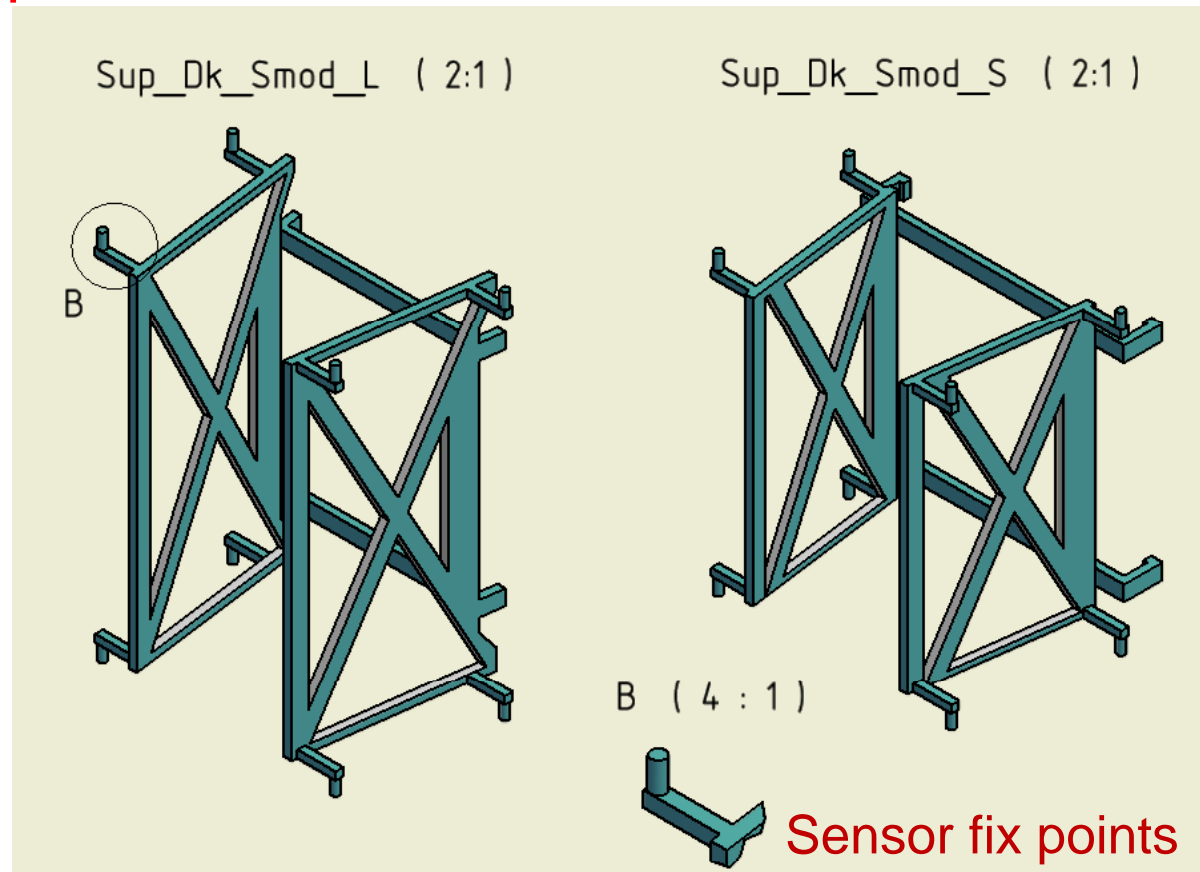


Concept for strip disks



- Implementation of the new disk concept

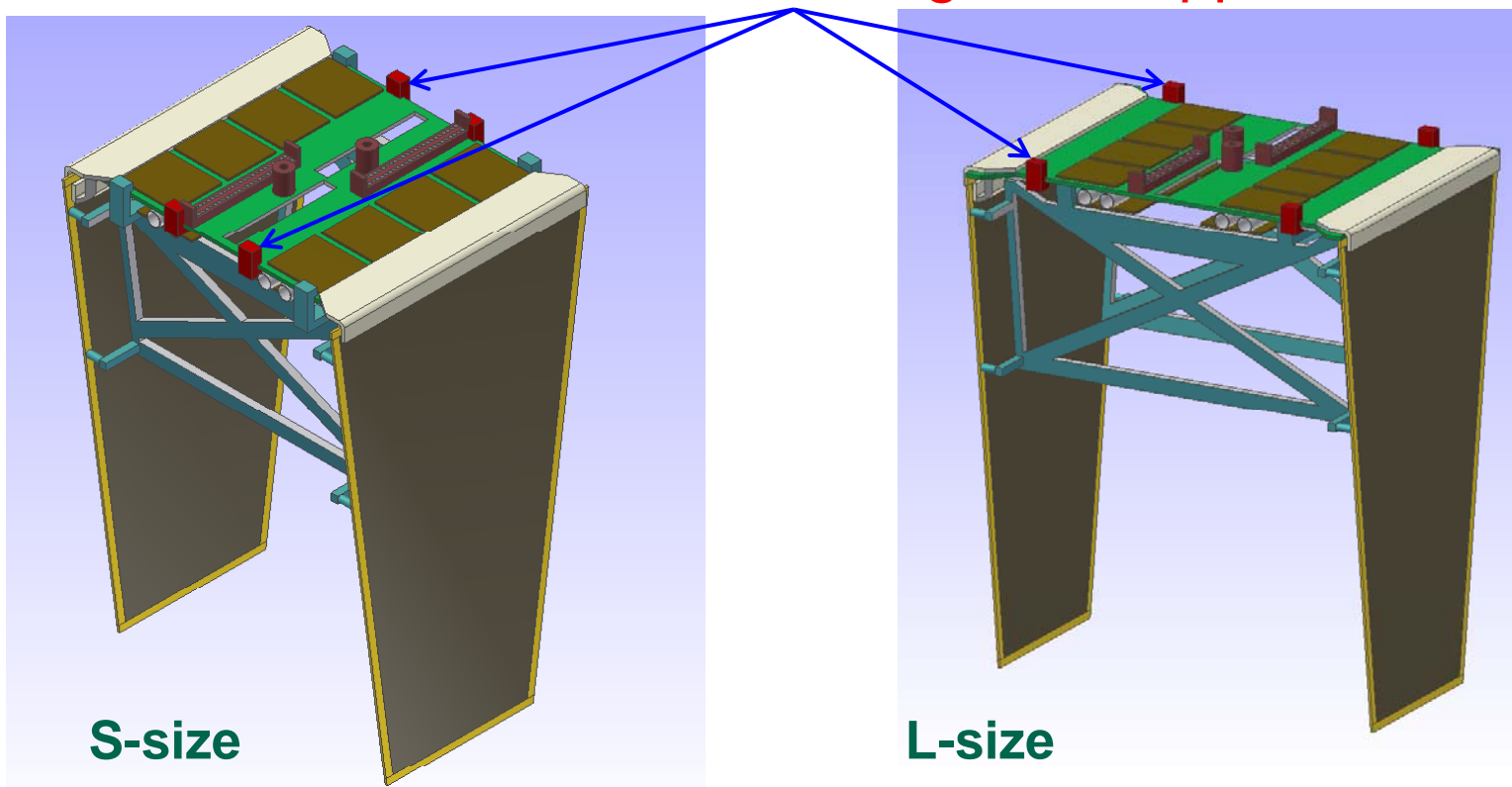
- **Support structure**



Concept for strip disks



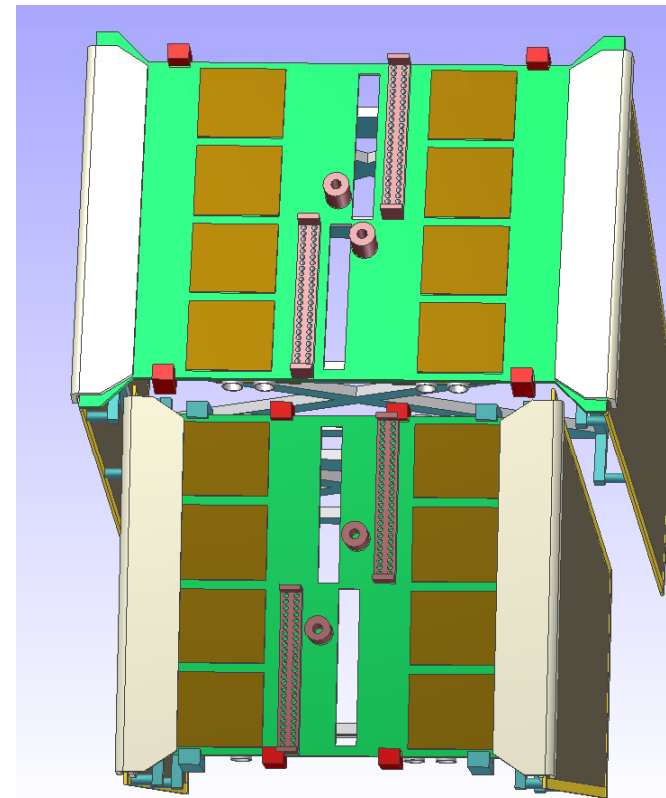
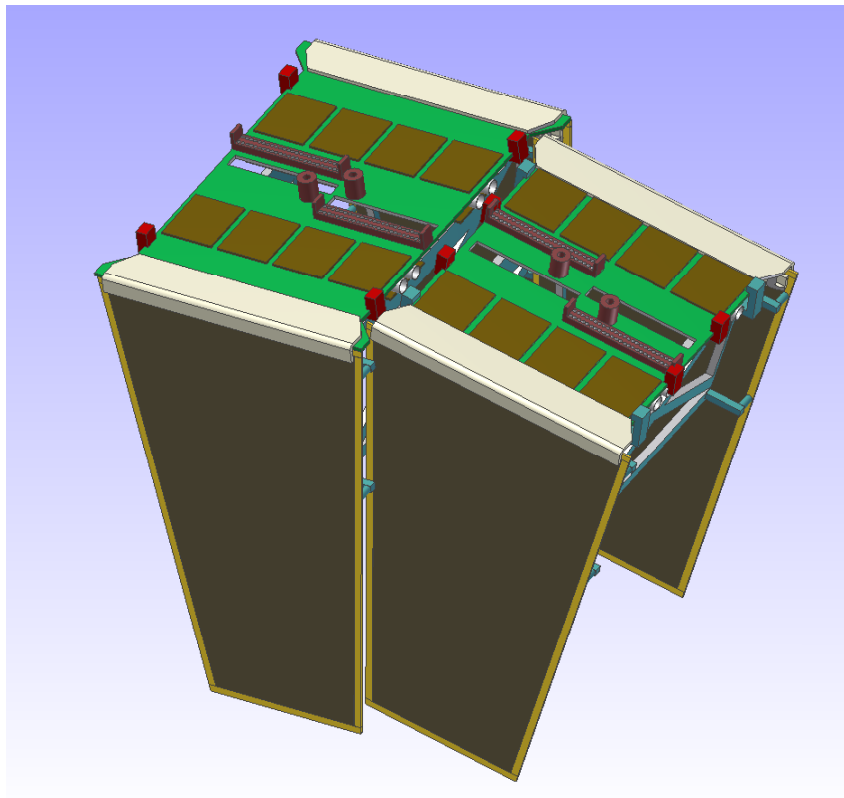
- Implementation of the new disk concept
 - Super-modules: Modules + support
+ connection to global support



Concept for strip disks



- Implementation of the new disk concept
 - Super-modules

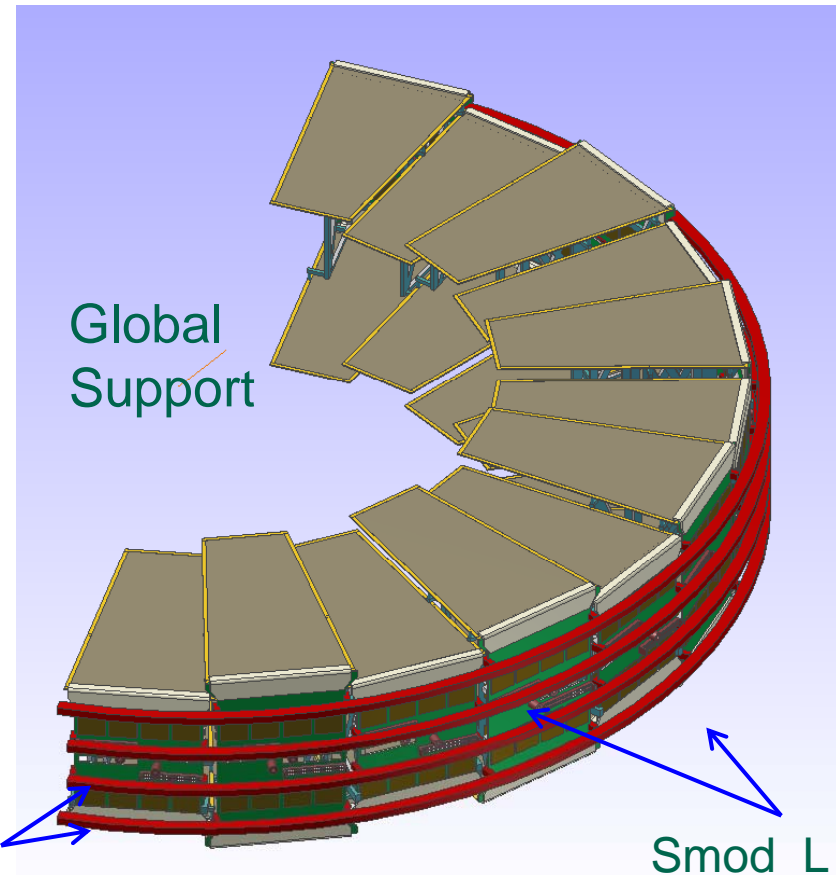
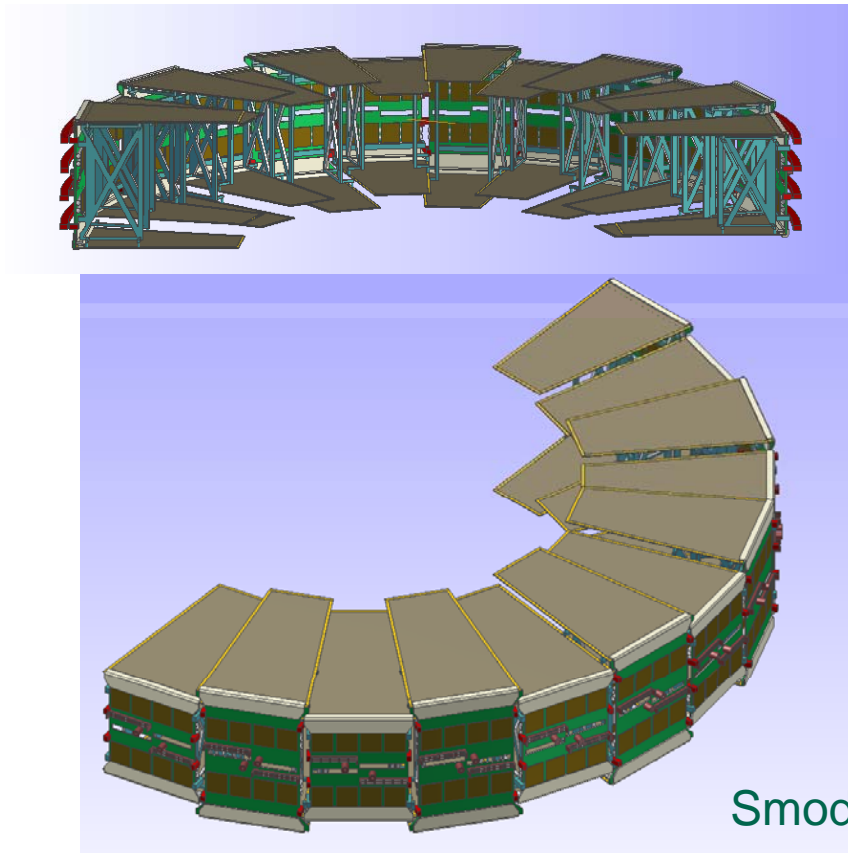


Concept for strip disks



- Implementation of the new disk concept

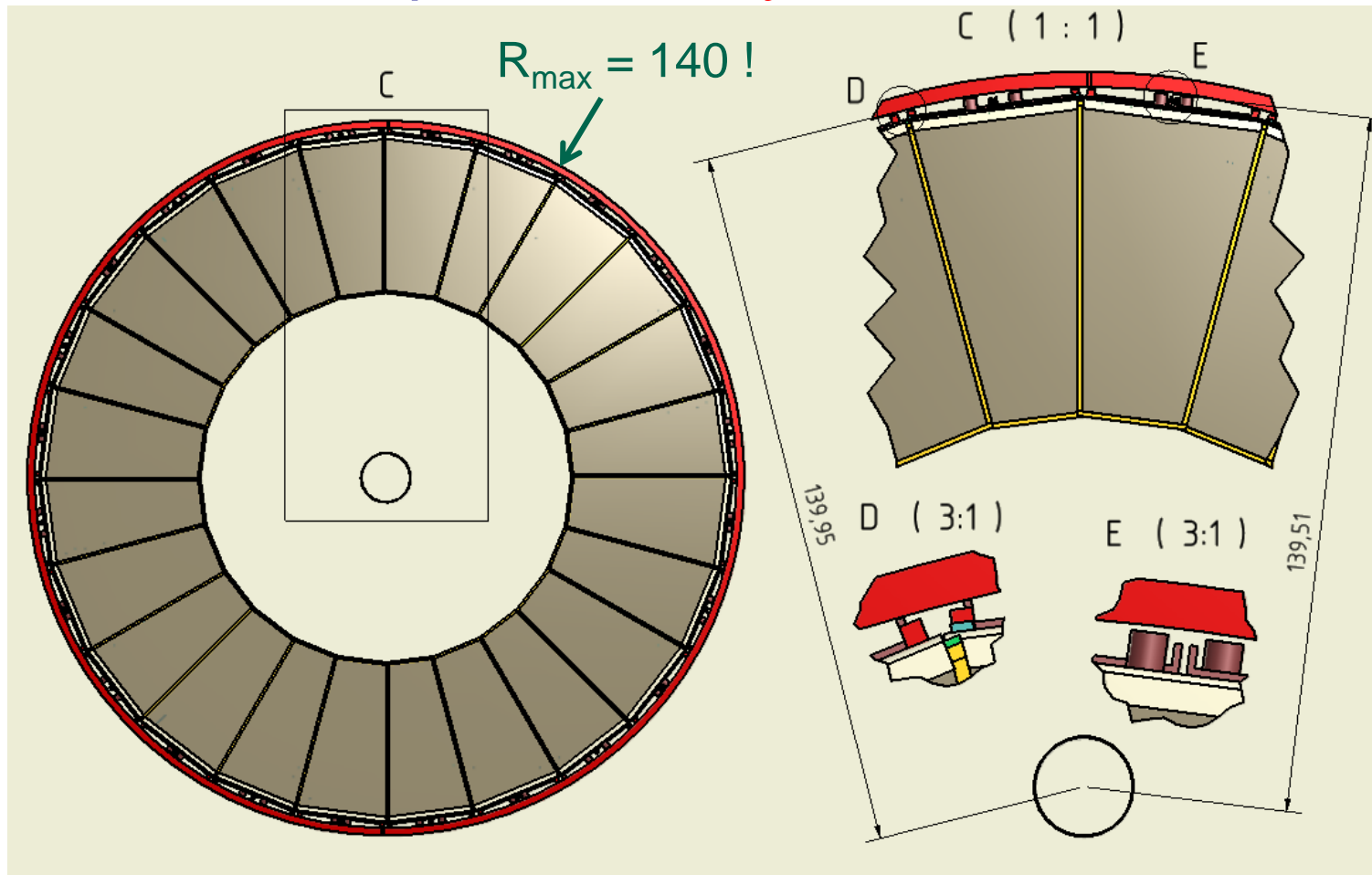
Disk layer / Forward part



Concept for strip disks



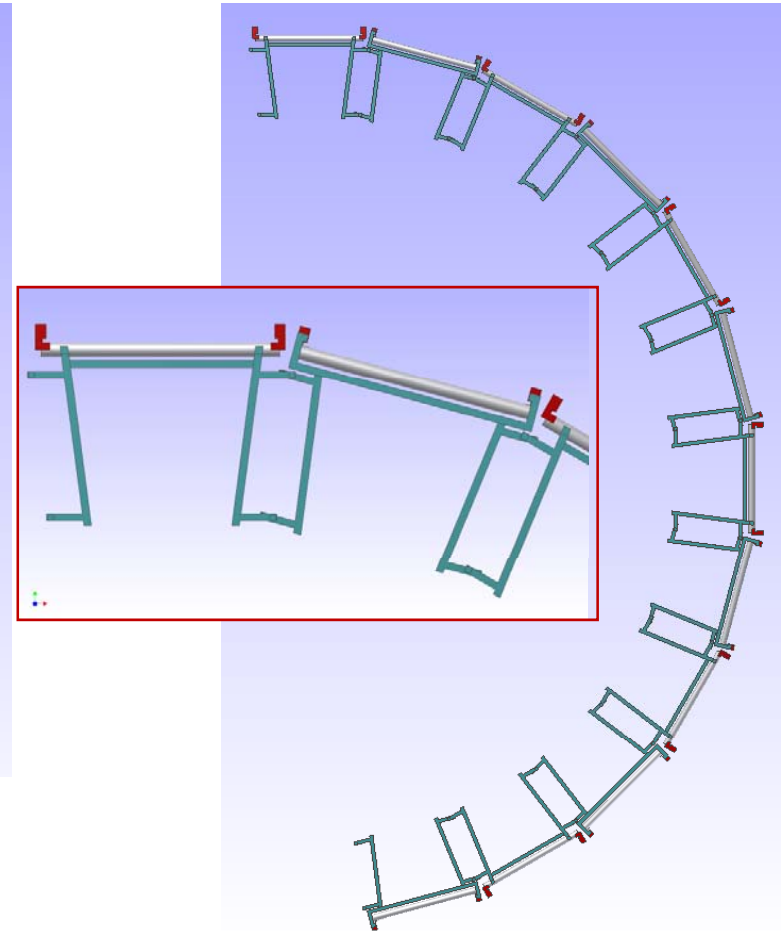
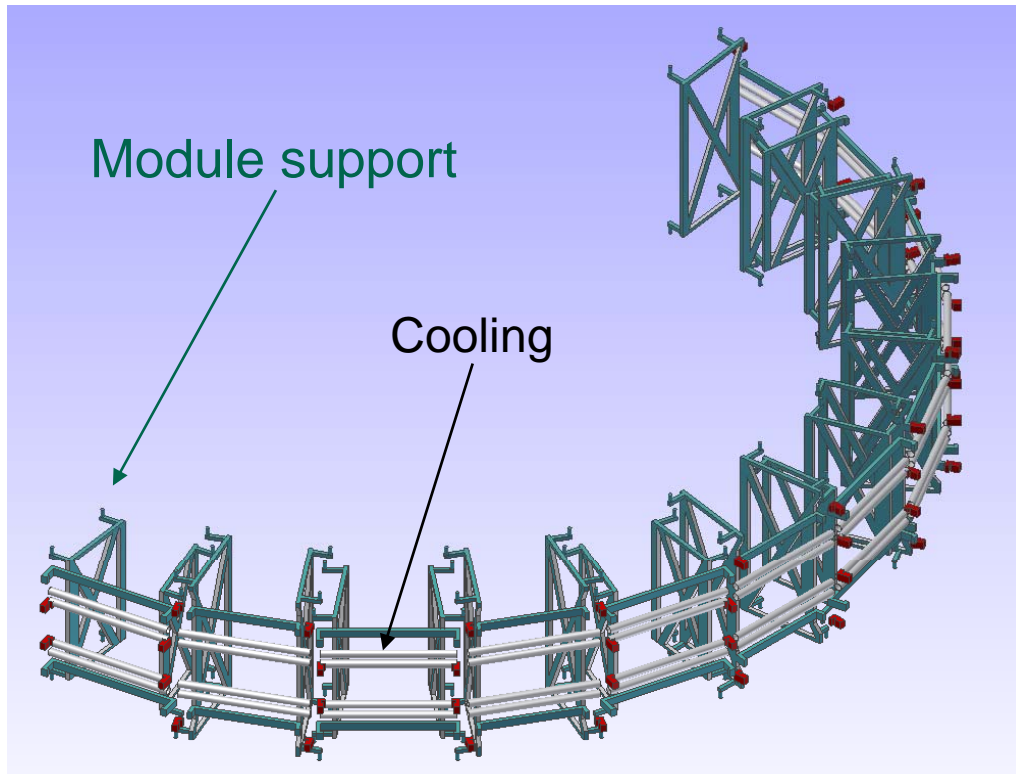
- New disk concept: **Boundary conditions fulfilled**



Concept for strip disks



- New disk concept: **Cooling + support**

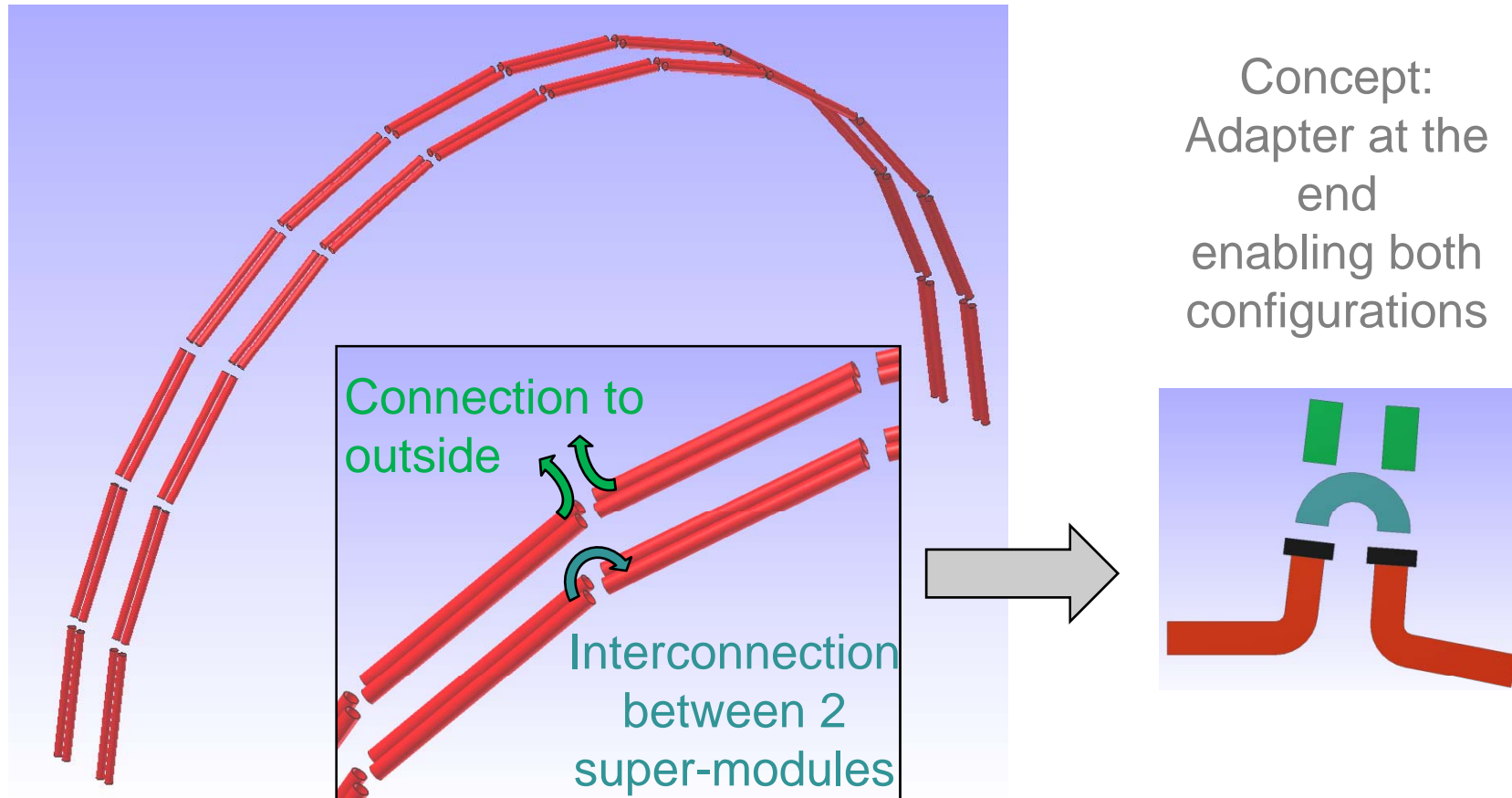


Connection to global support

Concept for strip disks



- New disk concept: **Cooling**



Summary and open items

Summary



- **Introduction of regularly MVD mechanics meetings**
 - In-person meetings of at least 2 days
 - Very efficient and very important for coordination at the current stage of development
- **Main topics at last meeting**
 - Pixel disks occupancy
 - Strip barrel design details and new strip disk concept
 - Cooling and integration items
 - Coordination of next steps
 - Open questions and to whom to address
- **Next meeting foreseen in Torino, April 2009**

Open items



- **Beam target geometry** ...more details in Mechanics session...
 - Axial position and aperture angle of cone (upstream)
 - Maximal angle $< 21^\circ$
 - Target pipe diameter
 - Clear definition inner / outer radius
 - Changes of section in the target pipe
 - Upstream flange in front of CF
 - Axial position and size

... Meeting (at least 2 day workshop) with beam-target group and other groups involved **urgently needed** ...

Open items



- **Cabling**
 - ✓ More details on numbers and spatial occupancy
- **Cooling**
 - ✓ Water cooling sufficient everywhere, especially for pixel part?
 - Best material for thin pipes is dependent on coolant!
 - ✓ What about sensor properties when working around 30°C?
 - ✓ Machining of thin pipes (\varnothing 2 mm):
 - Transforming a round shape to an elliptical one
 - Feasibility of bending → bending radius
- **Pixel super-modules**
 - ✓ Module sizes proposed in CAD models achievable?